

U.S.S.N. 09/827,106

In The Claims

Claim 9 has been cancelled without prejudice.

Claim 1 has been amended as follows:

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C 1. (Twice Amended) A matrix form semiconductor package substrate having an electrode situated in-between a plurality of integrated circuit (IC) package substrates for providing electrical communication to conductive pads situated on said ^{plurality of} IC package substrates comprising:

said plurality of IC package substrates integrally formed on a substrate strip in a matrix form having a boundary between each two of said plurality of IC package substrates, each of said plurality of IC package substrates having a multiplicity of conductive pads; and

said electrode formed in a rectangular-shaped, corrugated configuration along said boundary with each one of two legs of a corrugation connected to only one IC package substrate for providing electrical communication to said multiplicity of conductive pads and for providing insulation between said package substrates multiplicity of conductive pads after said plurality of IC packages are cut along said boundary through said electrode.

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Claim 11 has been amended as follows:

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11. (Twice Amended) A ball grid array (BGA) package substrate comprising:

an insulating substrate having a top surface;

a plurality of BGA package substrates formed on said top surface of said insulating substrate;

a multiplicity of conductive traces emanating from each one of said plurality of BGA package substrates, each of said multiplicity of conductive traces provides electrical communication between a conductive pad and a wirebond finger situated on said BGA package substrate; and

an electrode having a rectangular-shaped, corrugated configuration with each one of two legs of a corrugation connected to only one ^{BGA} ~~IE~~ package substrate.

REMARKS

Thorough examination and careful review of the application by the Examiner is noted and appreciated.

Claims 1-18 are pending in the application. Claims 1-18 stand rejected.

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